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REMARKS

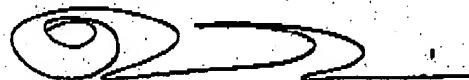
Claims 1-14 and 20 are pending. Claims 15-19 have been cancelled.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The first page of the marked-up version is captioned "VERSION WITH MARKINGS TO SHOW CHANGES MADE".

In view of the foregoing, Applicants believe all claims now pending in this Application are in condition for allowance. The issuance of a formal Notice of Allowance at an early date is respectfully requested.

If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at 650-326-2400.

Respectfully submitted,



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**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

1. (Unchanged) A module for dispensing material to a semiconductor processing tool, the module comprising:
  - a vessel including a first chamber and a second chamber, the vessel configured to receive the material from a bulk supply and to receive a pressurized flow of gas from a gas source; and
  - a valve assembly operable to selectively permit fluid communication between the first chamber and the second chamber during a non-refill module state and to prevent fluid communication between the first chamber and the second chamber during a refill module state.
2. (Unchanged) The module of claim 1 wherein the second chamber is in fluid communication with the semiconductor fabrication tool and in fluid communication with a pressurized gas supply.
3. (Unchanged) The module of claim 2 further comprising a pressure release valve in communication with the second chamber, the pressure release valve configured to automatically vent the second chamber when a pressure within the second chamber exceeds a cracking pressure.
4. (Unchanged) The module of claim 2 further comprising:
  - a processor;
  - a pressure release valve in communication with the second chamber; and
  - a pressure sensor positioned in the second chamber and in communication with the processor to activate the pressure release valve to vent the second chamber when a pressure within the second chamber exceeds a threshold value.

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5. (Unchanged) The module of claim 2 wherein:  
the first chamber includes a first port and a second port;  
the second chamber includes a first port and a second port, the first port in fluid communication with the semiconductor fabrication tool and the second port in fluid communication with the pressurized gas supply; and  
the valve assembly includes,  
a first control valve positioned between the first port of the first chamber and the first port of the second chamber,  
a second control valve positioned between the second port of the first chamber and the second port of the second chamber,  
a material supply valve positioned between the first port of the first chamber and a bulk material supply,  
a vent valve positioned between the second port of the first chamber and an outside environment;  
such that in the non-refill module state the first and second control valves are open, the material supply valve is closed, and the vent valve is closed, and in the refill module state the first and second control valves are closed, the material supply valve is open, and the vent valve is open.

6. (Unchanged) The module of claim 5 further comprising:  
a dispense valve positioned between the second port of the second chamber and the semiconductor processing tool; and  
a first fluid level sensor positioned in the second chamber and in electrical communication with the dispense valve, such that triggering of the first fluid level sensor automatically closes the dispense valve.

7. (Unchanged) The module of claim 6 further comprising:  
a processor; and

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a second fluid level sensor positioned in the second chamber at a level above the first fluid level sensor, the second fluid level sensor in communication with the processor such that triggering the second fluid level sensor automatically initiates a change from the non-refill module state to the refill module state.

8. (Unchanged) The module of claim 6 further comprising a first fluid level sensor positioned in the first chamber and in electrical communication with the material supply valve, such that triggering of the first fluid level sensor automatically closes the material supply valve.

9. (Unchanged) The module of claim 8 further comprising:  
a processor; and  
a second fluid level sensor positioned in the first chamber at a level below the first fluid level sensor, the second fluid level sensor in communication with a processor such that triggering of the second fluid level sensor initiates a change from the refill module state to the non-refill module state.

10. (Unchanged) The module of claim 2 wherein:  
the first chamber includes a first port, a second port, and a third port;  
the second chamber includes a first port, a second port, and a third port,  
the first port in fluid communication with the semiconductor fabrication tool and the second port in fluid communication with the pressurized gas supply; and  
the valve assembly includes,  
a first control valve positioned between the first port of the first chamber and the first port of the second chamber,  
a second control valve positioned between the third port of the first chamber and the third port of the second chamber,  
a material supply valve positioned between the second port of the first chamber and a bulk material supply,

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a vent valve positioned between the first port of the first chamber and an outside environment;

such that in the non-refill module state the first and second control valves are open, the material supply valve is closed, and the vent valve is closed, and in the refill module state the first and second control valves are closed, the material supply valve is open, and the vent valve is open

11. (Unchanged) The module of claim 10 further comprising:

a dispense valve positioned between the second port of the second chamber and the semiconductor processing tool; and

a first fluid level sensor positioned in the second chamber and in electrical communication with the dispense valve, such that triggering of the first fluid level sensor automatically closes the dispense valve.

12. (Unchanged) The module of claim 11 further comprising:

a processor; and

a second fluid level sensor positioned in the second chamber at a level above the first fluid level sensor, the second fluid level sensor in communication with the processor such that triggering of the second fluid level sensor automatically initiates a change from the non-refill module state to the refill module state.

13. (Unchanged) The module of claim 11 further comprising a first

fluid level sensor positioned in the first chamber and in electrical communication with the material supply valve, such that triggering of the first fluid level sensor automatically closes the material supply valve.

14. (Unchanged) The module of claim 13 further comprising:

a processor; and

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a second fluid level sensor positioned in the first chamber at a level below the first fluid level sensor, the second fluid level sensor in communication with a processor such that triggering of the second fluid level sensor initiates a change from the refill module state to the non-refill module state.

15.-19. Cancelled.

20. (Unchanged) A module for dispensing material to a semiconductor processing tool, the module comprising:

a vessel including a first chamber and a second chamber;

the first chamber including a first port and a second port, the first port configured to receive the material from a bulk supply through a material supply valve, and the second port in communication with an external environment through a vent valve,

the second chamber including a fluid level sensor, a first port, and a second port, the first port of the second chamber in fluid communication with a semiconductor processing tool through a dispense valve, the second port of the second chamber configured to receive a pressurized flow of gas from a pressurized gas supply through a gas inlet valve;

a pressure release valve in communication with the second port of the second chamber, the pressure release valve also in communication with the external environment;

a first control valve positioned between the first port of the first chamber and the first port of the second chamber; and

a second control valve positioned between the second port of the first chamber and the second port of the second chamber,

such that in the non-refill module state the first and second control valves are open, the material supply valve is closed, and the vent valve is closed, and in the refill module state the first and second control valves are closed, the material supply valve is

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open, and the vent valve is open, and transition between the non-refill module state and the module refill state is triggered by a drop in the material below the fluid level sensor.

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